

OL-PCF2003DUS

wafer level chip-scale package; 8 bumps; 1.16 x 0.86 x 0.48 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP8
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	17-8-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.13	-	1.16	1.19	mm
E	package width	0.83	-	0.86	0.89	mm
A	seated height	0.455	-	0.48	0.505	mm
A ₂	package height	0.365	-	0.38	0.395	mm
e	nominal pitch	-	-	0.28	-	mm
n ₂	actual quantity of termination	-	-	8	-	



2. Package outline

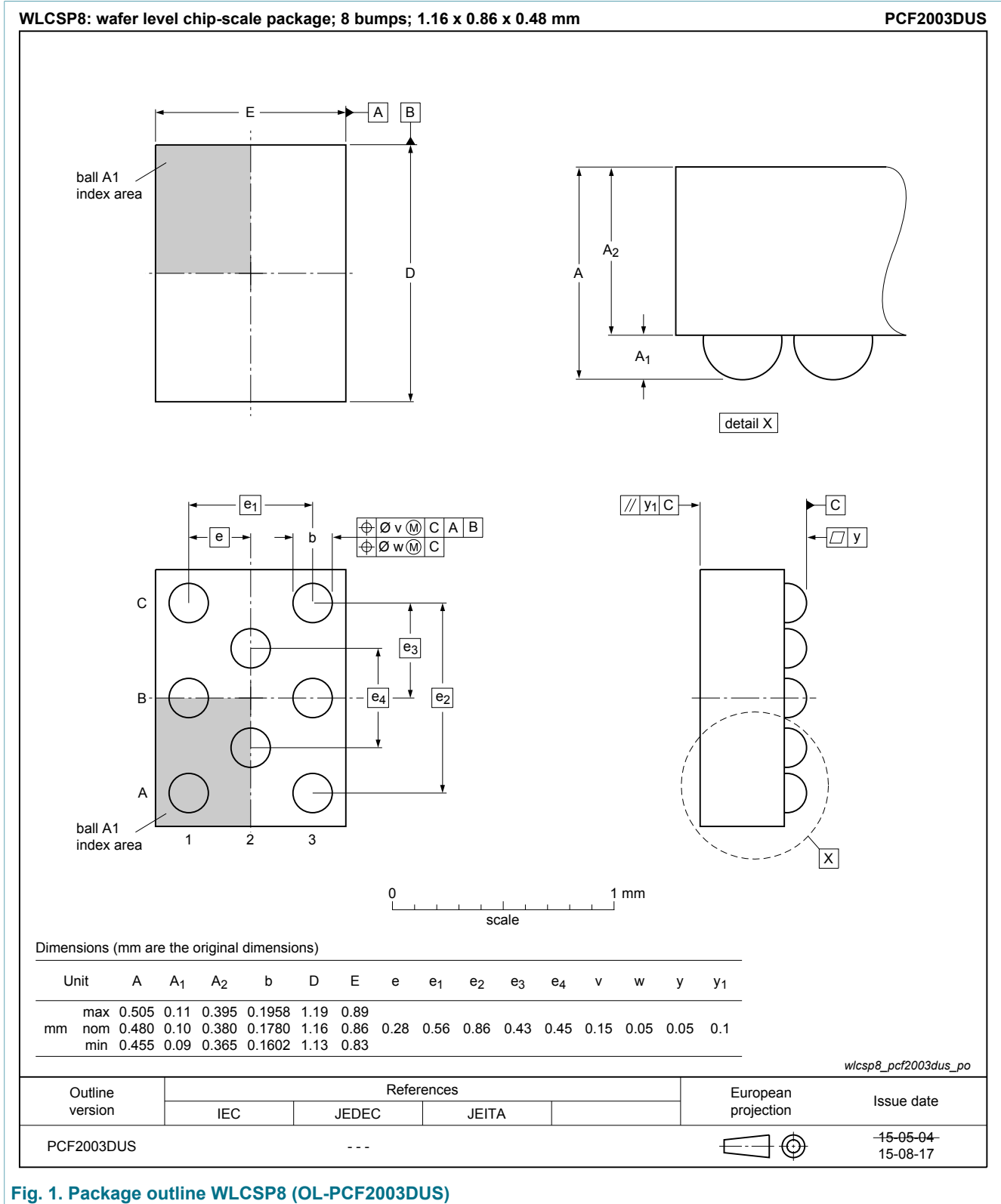


Fig. 1. Package outline WLCSP8 (OL-PCF2003DUS)

3. Legal information

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Date of release: 8 February 2016
